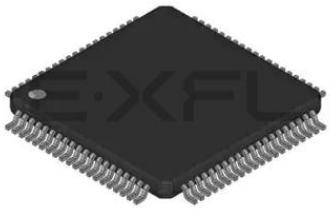
Infineon Technologies - XC886CM8FFA3V3ACKXUMA1 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 140°C (TA)
Mounting Type	-
Package / Case	-
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc886cm8ffa3v3ackxuma1

Features: (continued)

- Power-on reset generation
- Brownout detection for core logic supply
- On-chip OSC and PLL for clock generation
  - PLL loss-of-lock detection
- Power saving modes
  - slow-down mode
  - idle mode
  - power-down mode with wake-up capability via RXD or EXINT0
  - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Six ports
  - Up to 48 pins as digital I/O
  - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Four 16-bit timers
  - Timer 0 and Timer 1 (T0 and T1)
  - Timer 2 and Timer 21 (T2 and T21)
- Multiplication/Division Unit for arithmetic operations (MDU)
- Software libraries to support floating point and MDU calculations
- CORDIC Coprocessor for computation of trigonometric, hyperbolic and linear functions
- MultiCAN with 2 nodes, 32 message objects
- Capture/compare unit for PWM signal generation (CCU6)
- Two full-duplex serial interfaces (UART and UART1)
- Synchronous serial channel (SSC)
- On-chip debug support
  - 1 Kbyte of monitor ROM (part of the 12-Kbyte Boot ROM)
  - 64 bytes of monitor RAM
- Packages:
  - PG-TQFP-48
  - PG-TQFP-64
- Temperature range T_A:
  - SAF (-40 to 85 °C)
  - SAK (-40 to 125 °C)

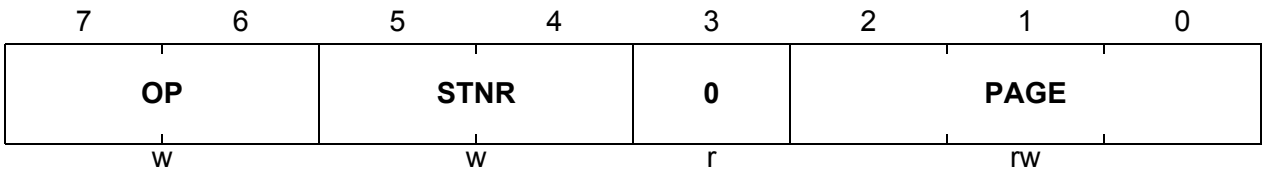
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
V_{DDP}	7, 17, 43/ 7, 25, 55	–	–	**I/O Port Supply (3.3 or 5.0 V)** Also used by EVR and analog modules. All pins must be connected.
V_{SSP}	18, 42/26, 54	–	–	**I/O Port Ground** All pins must be connected.
V_{DDC}	6/6	–	–	**Core Supply Monitor (2.5 V)**
V_{SSC}	5/5	–	–	**Core Supply Ground**
V_{AREF}	24/32	–	–	**ADC Reference Voltage**
V_{AGND}	23/31	–	–	**ADC Reference Ground**
XTAL1	4/4	I	Hi-Z	**External Oscillator Input (backup for on-chip OSC, normally NC)**
XTAL2	3/3	O	Hi-Z	**External Oscillator Output (backup for on-chip OSC, normally NC)**
TMS	10/16	I	PD	**Test Mode Select**
RESET	41/53	I	PU	**Reset Input**
MBC[1)]	44/58	I	PU	**Monitor & BootStrap Loader Control**
NC	–/56, 57	–	–	**No Connection**

1) An external pull-up device in the range of 4.7 kΩ to 100 kΩ. is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.

The page register has the following definition:

MOD_PAGE
Page Register for module MOD **Reset Value: 00_H**



Field	Bits	Type	Description
PAGE	[2:0]	rw	**Page Bits** When written, the value indicates the new page. When read, the value indicates the currently active page.
STNR	[5:4]	w	**Storage Number** This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10_B, the contents of PAGE are saved in STx before being overwritten with the new value. If OP = 11_B, the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored. 00 ST0 is selected. 01 ST1 is selected. 10 ST2 is selected. 11 ST3 is selected.

Table 10 Port Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0, PAGE 1										
80_H	**P0_PUDSEL Reset: FF_H** P0 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_PUDEN Reset: $C4_H$** P0 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_PUDSEL Reset: FF_H** P1 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_PUDEN Reset: FF_H** P1 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_PUDSEL Reset: FF_H** P5 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93_H	**P5_PUDEN Reset: FF_H** P5 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A0_H$	**P2_PUDSEL Reset: FF_H** P2 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_PUDEN Reset: 00_H** P2 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_PUDSEL Reset: BF_H** P3 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_PUDEN Reset: 40_H** P3 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C8_H$	**P4_PUDSEL Reset: FF_H** P4 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C9_H$	**P4_PUDEN Reset: 04_H** P4 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, PAGE 2										
80_H	**P0_ALTSEL0 Reset: 00_H** P0 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_ALTSEL1 Reset: 00_H** P0 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_ALTSEL0 Reset: 00_H** P1 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_ALTSEL1 Reset: 00_H** P1 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_ALTSEL0 Reset: 00_H** P5 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CD_H	**ADC_LCBR Reset: $B7_H$** Limit Check Boundary Register	Bit Field	BOUND1				BOUND0			
		Type	rw				rw			
CE_H	**ADC_INPCR0 Reset: 00_H** Input Class 0 Register	Bit Field	STC							
		Type	rw							
CF_H	**ADC_ETRCR Reset: 00_H** External Trigger Control Register	Bit Field	SYNEN1	SYNEN0	ETRSEL1			ETRSEL0		
		Type	rw	rw	rw			rw		
RMAP = 0, PAGE 1										
CA_H	**ADC_CHCTR0 Reset: 00_H** Channel Control Register 0	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CB_H	**ADC_CHCTR1 Reset: 00_H** Channel Control Register 1	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CC_H	**ADC_CHCTR2 Reset: 00_H** Channel Control Register 2	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CD_H	**ADC_CHCTR3 Reset: 00_H** Channel Control Register 3	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CE_H	**ADC_CHCTR4 Reset: 00_H** Channel Control Register 4	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CF_H	**ADC_CHCTR5 Reset: 00_H** Channel Control Register 5	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D2_H$	**ADC_CHCTR6 Reset: 00_H** Channel Control Register 6	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D3_H$	**ADC_CHCTR7 Reset: 00_H** Channel Control Register 7	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
RMAP = 0, PAGE 2										
CA_H	**ADC_RESR0L Reset: 00_H** Result Register 0 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CB_H	**ADC_RESR0H Reset: 00_H** Result Register 0 High	Bit Field	RESULT							
		Type	rh							
CC_H	**ADC_RESR1L Reset: 00_H** Result Register 1 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CD_H	**ADC_RESR1H Reset: 00_H** Result Register 1 High	Bit Field	RESULT							
		Type	rh							
CE_H	**ADC_RESR2L Reset: 00_H** Result Register 2 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CF_H	**ADC_RESR2H Reset: 00_H** Result Register 2 High	Bit Field	RESULT							
		Type	rh							
$D2_H$	**ADC_RESR3L Reset: 00_H** Result Register 3 Low	Bit Field	RESULT		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		

Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FB_H	**CCU6_CC60RH** **Reset: 00_H** Capture/Compare Register for Channel CC60 High	Bit Field	CC60VH							
		Type	rh							
FC_H	**CCU6_CC61RL** **Reset: 00_H** Capture/Compare Register for Channel CC61 Low	Bit Field	CC61VL							
		Type	rh							
FD_H	**CCU6_CC61RH** **Reset: 00_H** Capture/Compare Register for Channel CC61 High	Bit Field	CC61VH							
		Type	rh							
FE_H	**CCU6_CC62RL** **Reset: 00_H** Capture/Compare Register for Channel CC62 Low	Bit Field	CC62VL							
		Type	rh							
FF_H	**CCU6_CC62RH** **Reset: 00_H** Capture/Compare Register for Channel CC62 High	Bit Field	CC62VH							
		Type	rh							
RMAP = 0, PAGE 2										
$9A_H$	**CCU6_T12MSELL** **Reset: 00_H** T12 Capture/Compare Mode Select Register Low	Bit Field	MSEL61				MSEL60			
		Type	rw				rw			
$9B_H$	**CCU6_T12MSELH** **Reset: 00_H** T12 Capture/Compare Mode Select Register High	Bit Field	DBYP	HSYNC			MSEL62			
		Type	rw	rw			rw			
$9C_H$	**CCU6_IENL** **Reset: 00_H** Capture/Compare Interrupt Enable Register Low	Bit Field	ENT12PM	ENT12OM	ENCC62F	ENCC62R	ENCC61F	ENCC61R	ENCC60F	ENCC60R
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$9D_H$	**CCU6_IENH** **Reset: 00_H** Capture/Compare Interrupt Enable Register High	Bit Field	ENSTR	ENIDLE	ENWHE	ENCHE	0	ENTRPF	ENT13PM	ENT13CM
		Type	rw	rw	rw	rw	r	rw	rw	rw
$9E_H$	**CCU6_INPL** **Reset: 40_H** Capture/Compare Interrupt Node Pointer Register Low	Bit Field	INPCHE		INPCC62		INPCC61		INPCC60	
		Type	rw		rw		rw		rw	
$9F_H$	**CCU6_INPH** **Reset: 39_H** Capture/Compare Interrupt Node Pointer Register High	Bit Field	0		INPT13		INPT12		INPERR	
		Type	r		rw		rw		rw	
$A4_H$	**CCU6_ISSL** **Reset: 00_H** Capture/Compare Interrupt Status Set Register Low	Bit Field	ST12PM	ST12OM	SCC62F	SCC62R	SCC61F	SCC61R	SCC60F	SCC60R
		Type	w	w	w	w	w	w	w	w
$A5_H$	**CCU6_ISSH** **Reset: 00_H** Capture/Compare Interrupt Status Set Register High	Bit Field	SSTR	SIDLE	SWHE	SCHE	SWHC	STRPF	ST13PM	ST13CM
		Type	w	w	w	w	w	w	w	w
$A6_H$	**CCU6_PSLR** **Reset: 00_H** Passive State Level Register	Bit Field	PSL63	0	PSL					
		Type	rwh	r	rwh					
$A7_H$	**CCU6_MCMCTR** **Reset: 00_H** Multi-Channel Mode Control Register	Bit Field	0		SWSYN		0	SWSEL		
		Type	r		rw		r	rw		
FA_H	**CCU6_TCTR2L** **Reset: 00_H** Timer Control Register 2 Low	Bit Field	0	T13TED	T13TEC				T13SSC	T12SSC
		Type	r	rw	rw				rw	rw

Table 18 OCDS Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
EC_H	**MMWR2** **Reset: 00_H** Monitor Work Register 2	Bit Field	MMWR2							
		Type	rw							

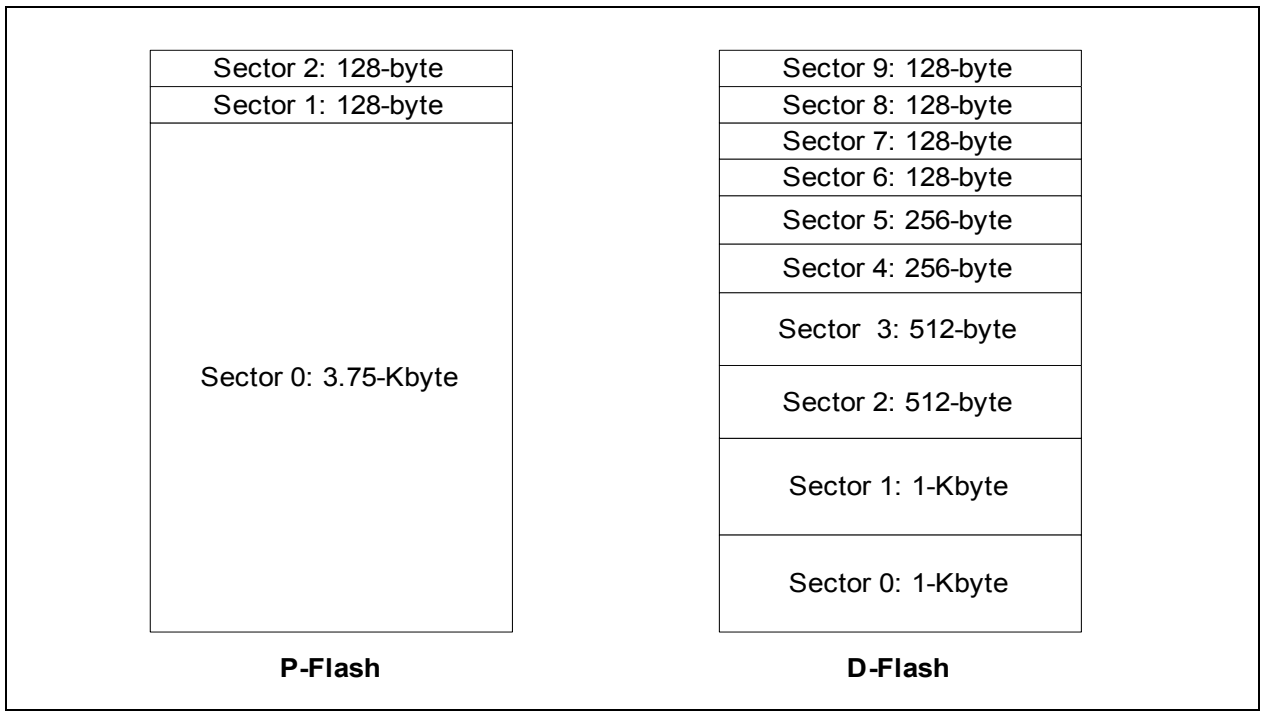


Figure 11 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

3.3.2 Parallel Read Access of P-Flash

To enhance system performance, the P-Flash banks are configured for parallel read to allow two bytes of linear code to be read in 4 x CCLK cycles, compared to 6 x CCLK cycles if serial read is performed. This is achieved by reading two bytes in parallel from a P-Flash bank pair within the 3 x CCLK cycles access time and storing them in a cache. Subsequent read from the cache by the CPU does not require a wait state and can be completed within 1 x CCLK cycle. The result is the average instruction fetch time from the P-Flash banks is reduced and thus, the MIPS (Mega Instruction Per Second) of the system is increased.

However, if the parallel read feature is not desired due to certain timing constraints, it can be disabled by calling the parallel read disable subroutine.

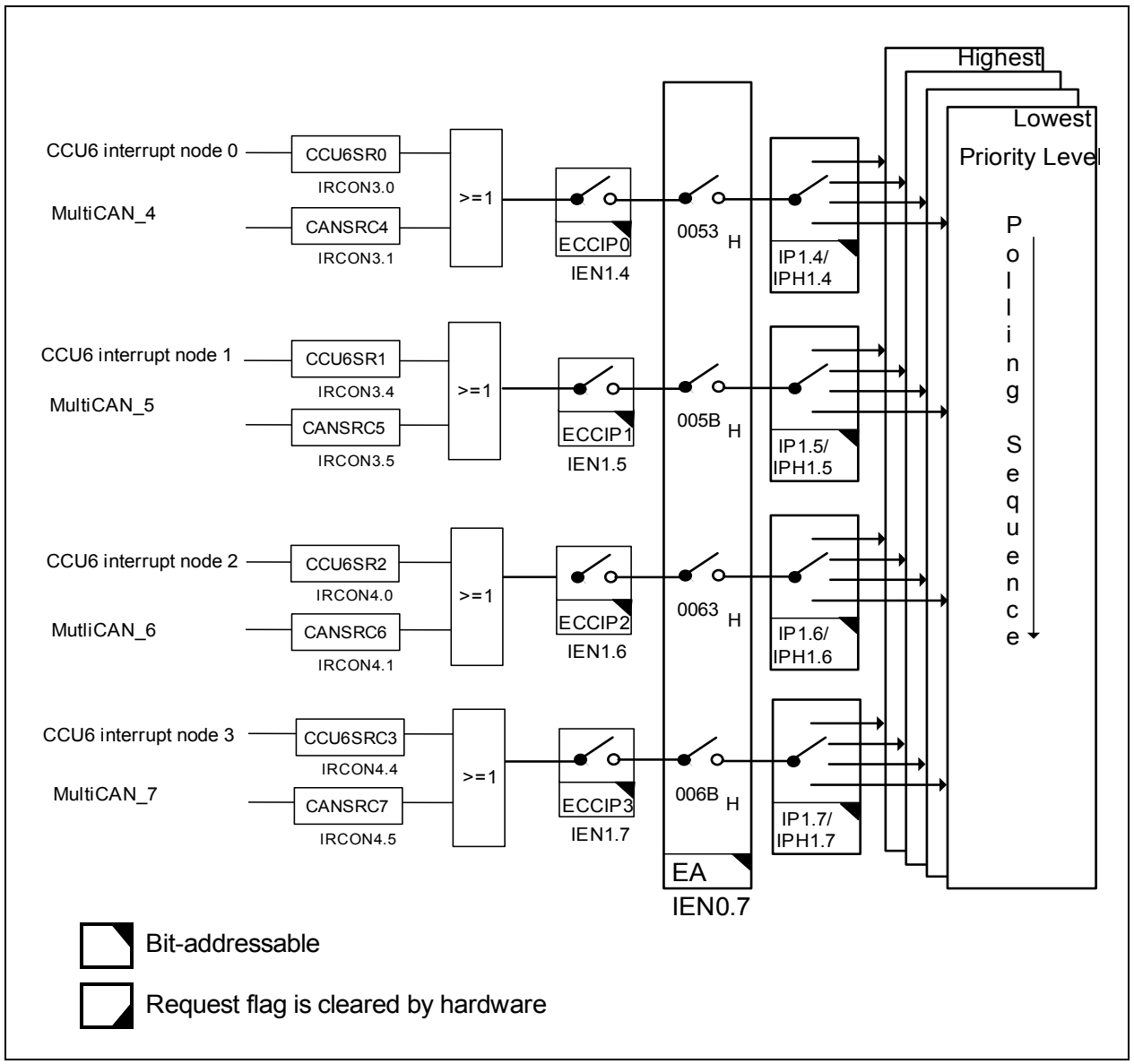


Figure 18 Interrupt Request Sources (Part 5)

3.5 Parallel Ports

The XC886 has 34 port pins organized into five parallel ports, Port 0 (P0) to Port 4 (P4), while the XC888 has 48 port pins organized into six parallel ports, Port 0 (P0) to Port 5 (P5). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1, P3, P4 and P5 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

3.6 Power Supply System with Embedded Voltage Regulator

The XC886/888 microcontroller requires two different levels of power supply:

- 3.3 V or 5.0 V for the Embedded Voltage Regulator (EVR) and Ports
- 2.5 V for the core, memory, on-chip oscillator, and peripherals

Figure 21 shows the XC886/888 power supply system. A power supply of 3.3 V or 5.0 V must be provided from the external power supply pin. The 2.5 V power supply for the logic is generated by the EVR. The EVR helps to reduce the power consumption of the whole chip and the complexity of the application board design.

The EVR consists of a main voltage regulator and a low power voltage regulator. In active mode, both voltage regulators are enabled. In power-down mode, the main voltage regulator is switched off, while the low power voltage regulator continues to function and provide power supply to the system with low power consumption.

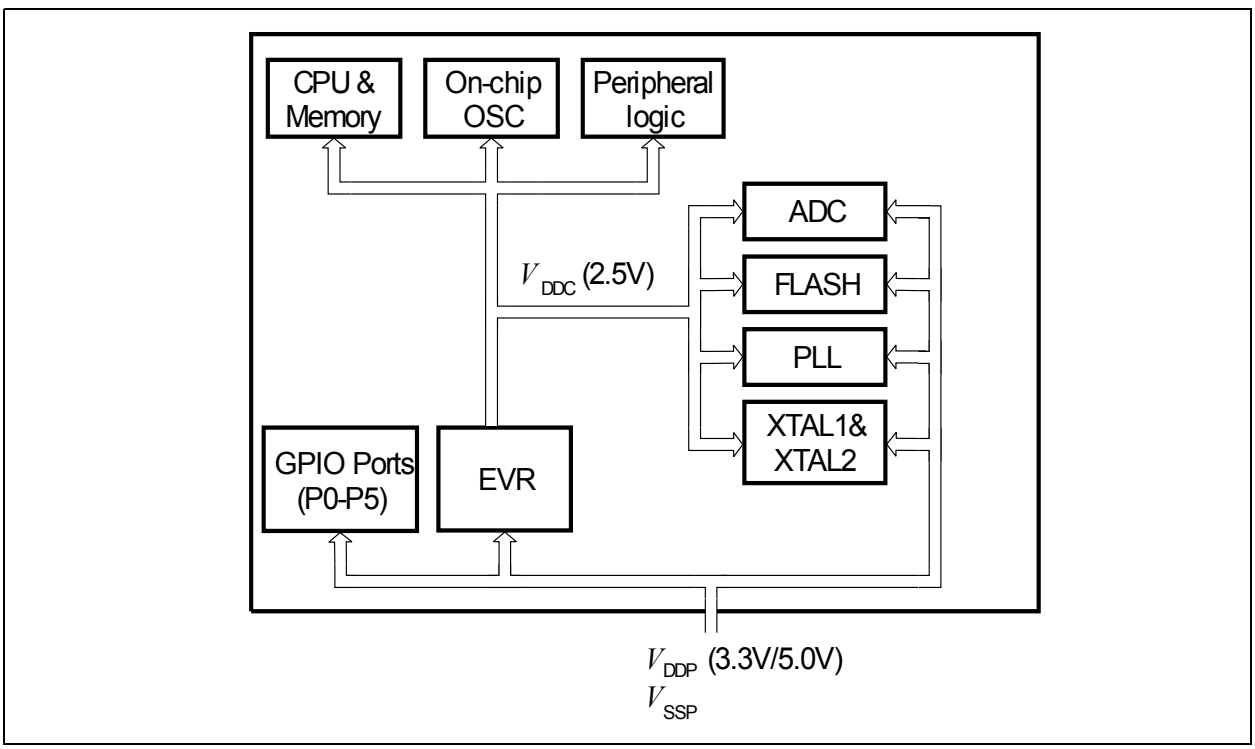


Figure 21 XC886/888 Power Supply System

EVR Features

- Input voltage (V_{DDP}): 3.3 V/5.0 V
- Output voltage (V_{DDC}): 2.5 V ± 7.5%
- Low power voltage regulator provided in power-down mode
- V_{DDC} and V_{DDP} prewarning detection
- V_{DDC} brownout detection

3.9 Power Saving Modes

The power saving modes of the XC886/888 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see **Figure 27**) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

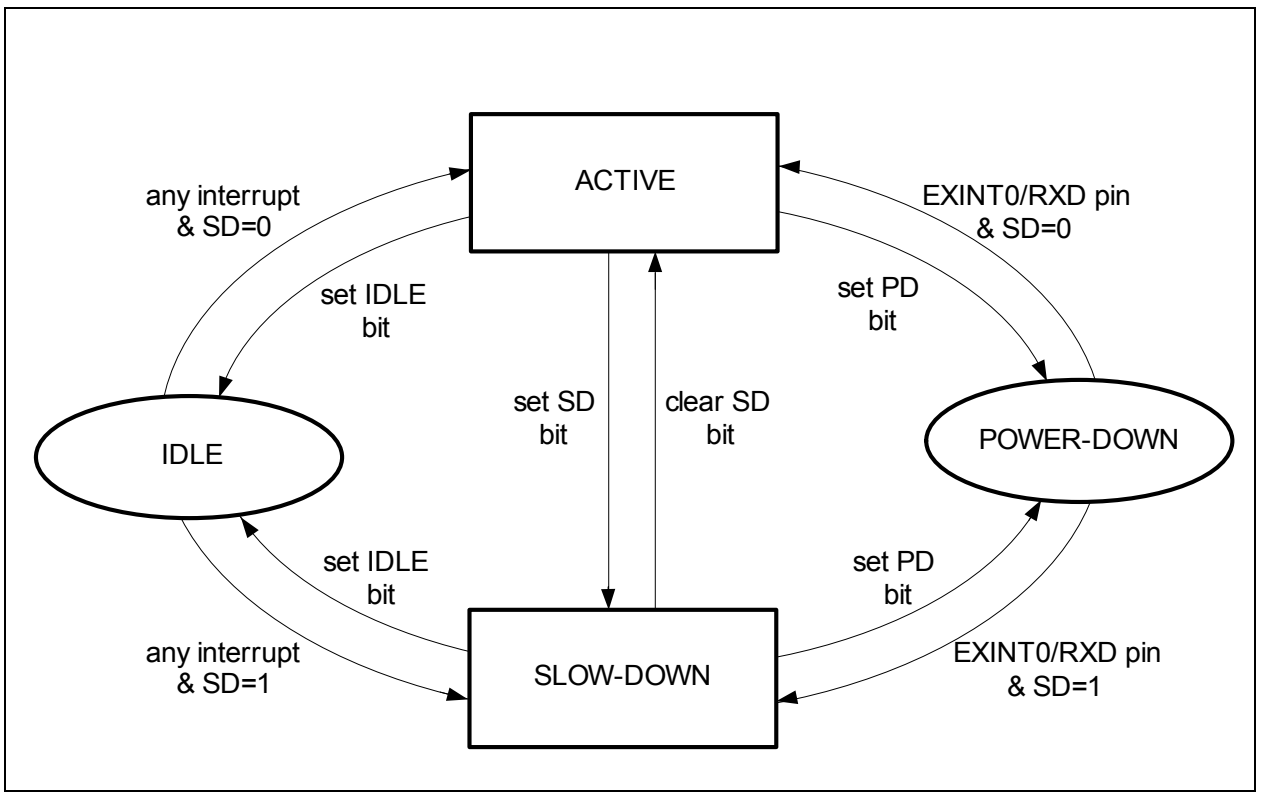


Figure 27 Transition between Power Saving Modes

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert FNMIWDT) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2^8). The time period for an overflow of the WDT is programmable in two ways:

- The input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- The reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}} \quad (3.4)$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 29**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB cannot be smaller than WDTREL.

3.18 Timer 2 and Timer 21

Timer 2 and Timer 21 are 16-bit general purpose timers (THL2) that are fully compatible and have two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode, see **Table 33**. As a timer, the timers count with an input clock of PCLK/12 (if prescaler is disabled). As a counter, they count 1-to-0 transitions on pin T2. In the counter mode, the maximum resolution for the count is PCLK/24 (if prescaler is disabled).

Table 33 Timer 2 Modes

Mode	Description
Auto-reload	**Up/Down Count Disabled** • Count up only • Start counting from 16-bit reload value, overflow at $FFFF_H$ • Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well • Programmble reload value in register RC2 • Interrupt is generated with reload event
	Up/Down Count Enabled • Count up or down, direction determined by level at input pin T2EX • No interrupt is generated • Count up – Start counting from 16-bit reload value, overflow at $FFFF_H$ – Reload event triggered by overflow condition – Programmble reload value in register RC2 • Count down – Start counting from $FFFF_H$, underflow at value defined in register RC2 – Reload event triggered by underflow condition – Reload value fixed at $FFFF_H$
Channel capture	• Count up only • Start counting from 0000_H, overflow at $FFFF_H$ • Reload event triggered by overflow condition • Reload value fixed at 0000_H • Capture event triggered by falling/rising edge at pin T2EX • Captured timer value stored in register RC2 • Interrupt is generated with reload or capture event

3.19 Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

Timer T13 Features

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

The block diagram of the CCU6 module is shown in **Figure 33**.

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis on port pins	$HYSP$	CC	0.07 × V_{DDP}	–	V	CMOS Mode[1)]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1)]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX}	SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	
Pull-up current	I_{PU}	SR	–	-10	µA	$V_{IHP,min}$
			-150	–	µA	$V_{ILP,max}$
Pull-down current	I_{PD}	SR	–	10	µA	$V_{ILP,max}$
			150	–	µA	$V_{IHP,min}$
Input leakage current	I_{OZ1}	CC	-1	1	µA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125°C$[2)]
Input current at XTAL1	I_{ILX}	CC	-10	10	µA	
Overload current on any pin	I_{OV}	SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma\|I_{OV}\|$	SR	–	25	mA	[3)]
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	[4)]
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M SR	SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma\|I_M\|$	SR	–	90	mA	
Maximum current into V_{DDP}	I_{MVDDP}	SR	–	120	mA	[3)]

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	[3]
V_{DDP} = 3.3 V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on RESET pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode[1]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	

4.2.2 Supply Threshold Characteristics

Table 39 provides the characteristics of the supply threshold in the XC886/888.

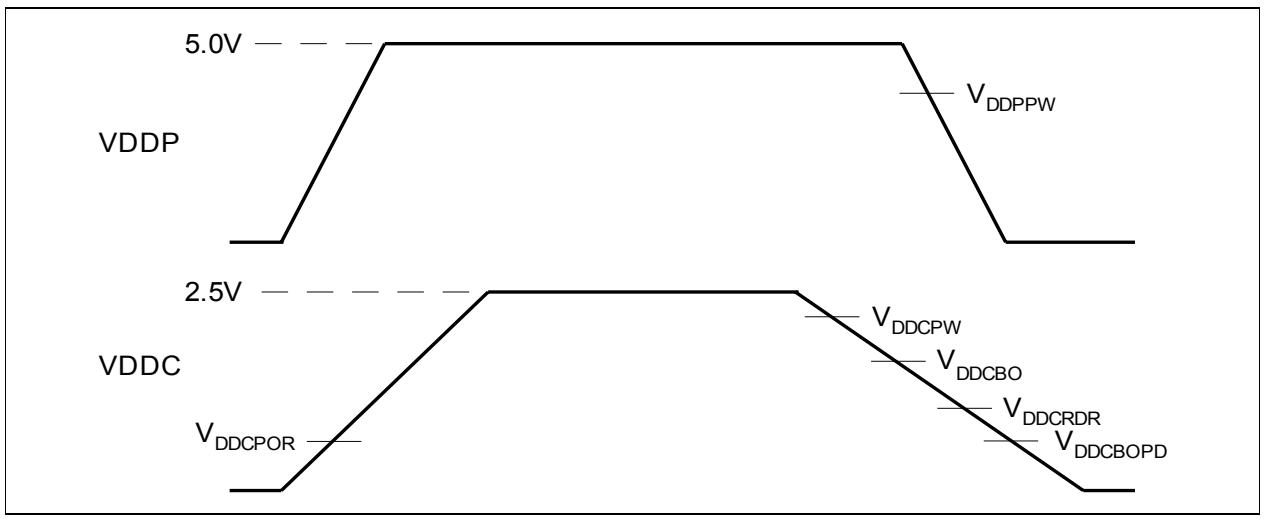


Figure 38 Supply Threshold Parameters

Table 39 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit
			min.	typ.	max.	
V_{DDC} prewarning voltage[1)]	V_{DDCPW}	CC	2.2	2.3	2.4	V
V_{DDC} brownout voltage in active mode[1)]	V_{DDCBO}	CC	2.0	2.1	2.2	V
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V
V_{DDC} brownout voltage in power-down mode[2)]	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V
V_{DDP} prewarning voltage[3)]	V_{DDPPW}	CC	3.4	4.0	4.6	V
Power-on reset voltage[2)4)]	V_{DDCPOR}	CC	1.3	1.5	1.7	V

1) Detection is disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V.
Detection must be disabled for external power supply of 3.3V.

4) The reset of EVR is extended by 300 µs typically after the VDDC reaches the power-on reset voltage.

4.2.3.1 ADC Conversion Timing

Conversion time, $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$, where

r = CTC + 2 for CTC = 00_B, 01_B or 10_B,

r = 32 for CTC = 11_B,

CTC = Conversion Time Control (GLOBCTR.CTC),

STC = Sample Time Control (INPCR0.STC),

n = 8 or 10 (for 8-bit and 10-bit conversion respectively),

$t_{ADC} = 1 / f_{ADC}$